

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc2960hts8-4#trmpbf

(Engineering Calculation)

TSOT-23

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**TOTAL MASS (g) : 0.012149**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000454	1000000	37370.28125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.004582	975000	377159.96875		
		Iron (Fe)	7439-89-6	0.000113	24000	9301.4140625		
		Phosphorus (P)	7723-14-0	0.000001	300	82.3133926392		
		Zinc (Zn)	7440-66-6	0.000003	700	246.940216064		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.004699</b>	<b>1000000</b>	<b>386790.65625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000663	1000000	54548.2617188		
		<b>External Plating Total:</b>				<b>0.000663</b>	<b>1000000</b>	<b>54548.2617188</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000080	1000000	6585.07177734		
<b>Internal Plating Total:</b>				<b>0.000080</b>	<b>1000000</b>	<b>6585.07177734</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000147	800000	12100.0693359		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000037	200000	3045.59594727		
<b>Die Attach Total:</b>				<b>0.000184</b>	<b>1000000</b>	<b>15145.6660156</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000347	58000	28562.7480469		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.005322	890000	438071.90625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000299	50000	24611.7050781		
		Carbon Black (C)	1333-86-4	0.000012	2000	987.760864258		
		<b>Encapsulation Total:</b>				<b>0.005980</b>	<b>1000000</b>	<b>492234.125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000089	1000000	7325.89257812		
					<b>TOTAL MASS (g) :</b>	<b>0.012149</b>		